



### Power Field Effect Transistor

### **GENERAL DESCRIPTION**

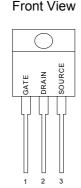
This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

#### **FEATURES**

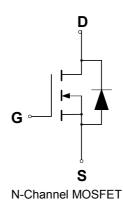
- Reduced Gate Charge
- ◆ Ultra Low On-Resistance Provides Higher Efficiency
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- ♦ I<sub>DSS</sub> and V<sub>DS</sub>(on) Specified at Elevated Temperature

### PIN CONFIGURATION

#### **SYMBOL**



TO-220/TO-220FP



### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain to Current — Continuous		9.5	Α
- Pulsed	$I_{DM}$	28.5	
Gate-to-Source Voltage — Continue	$V_{GS}$	±30	V
Total Power Dissipation – TO220	$P_D$	185	W
– TO220FP		48	
Derate above 25℃ - TO220		1.45	W/°C
– TO220FP		0.38	
Operating and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to 150	$^{\circ}\!\mathbb{C}$
Single Pulse Drain-to-Source Avalanche Energy $-T_J = 25^{\circ}$ C ( $V_{DD} = 100V$ , $V_{GS} = 10V$ , $I_L = 8A$ , $L = 10mH$ , $R_G = 25\Omega$ )	E <sub>AS</sub>	320	mJ
Thermal Resistance — Junction to Case -TO220	θЈС	0.7	°C/W
<ul> <li>Junction to Case -TO220FP</li> </ul>		3.4	
<ul> <li>Junction to Ambient -TO220, TO220FP</li> </ul>	$\theta_{JA}$	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	$T_L$	260	$^{\circ}\!\mathbb{C}$





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### **ORDERING INFORMATION**

Part Number	Package
GPT10N60GN220	TO-220
GPT10N60DGN220FP	TO-220 Full Package

<sup>\*</sup>Note: G: Suffix for Pb Free Product

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified,  $T_J = 25^{\circ}C$ .

			GPT10N60			
Characteristic		Symbol	Min	Тур	Max	Units
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	600			V
$(V_{GS} = 0 \text{ V}, I_D = 250 \ \mu \text{ A})$						
Drain-Source Leakage Current		I <sub>DSS</sub>			1	uA
$(V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V})$						
Gate-Source Leakage Current-Forward		I <sub>GSSF</sub>			100	nA
$(V_{gsf} = 30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Reverse		$I_{GSSR}$			100	nA
$(V_{gsr} = 30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate Threshold Voltage		$V_{GS(th)}$	3	4	5	V
$(V_{DS} = V_{GS}, I_{D} = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5A) *		R <sub>DS(on)</sub>			0.76	Ω
Forward Transconductance (V <sub>DS</sub> = 15 V, I <sub>D</sub> = 5A) *		<b>g</b> <sub>FS</sub>		8		S
Input Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	C <sub>iss</sub>		1467		pF
Output Capacitance	$(v_{DS} - 25 \text{ V}, v_{GS} - 0 \text{ V},$ f = 1.0  MHz)	Coss		135		pF
Reverse Transfer Capacitance	f = 1.0 MH2)	C <sub>rss</sub>		9.3		pF
Turn-On Delay Time	$(V_{DD} = 300 \text{ V}, I_D = 10 \text{ A},$ $V_{GS} = 10 \text{ V},$ $R_G = 9.1\Omega) *$	$t_{d(on)}$		26.6		ns
Rise Time		t <sub>r</sub>		20.8		ns
Turn-Off Delay Time		$t_{d(off)}$		48		ns
Fall Time		t <sub>f</sub>		25.6		ns
Total Gate Charge	$(V_{DS} = 480 \text{ V}, I_{D} = 10 \text{ A},$	$Q_g$		32.4		nC
Gate-Source Charge		$Q_{gs}$		6.61		nC
Gate-Drain Charge	$V_{GS} = 10 \text{ V})^*$	$Q_{gd}$		12.7		nC
SOURCE-DRAIN DIODE CHARACTE	RISTICS	-				
Forward On-Voltage(1)	$(I_S = 10A, V_{GS} = 0 V,$	V <sub>SD</sub>			1.5	V
Forward Turn-On Time		t <sub>on</sub>		**		ns
Reverse Recovery Time	$d_{IS}/d_t = 100A/\mu s$ )	t <sub>rr</sub>		412		ns

<sup>\*</sup> Pulse Test: Pulse Width  $\leq$ 300 $\mu$ s, Duty Cycle  $\leq$ 2%

<sup>\*\*</sup> Negligible, Dominated by circuit inductance



## POWER FIELD EFFECT TRANSISTOR

### TYPICAL ELECTRICAL CHARACTERISTICS

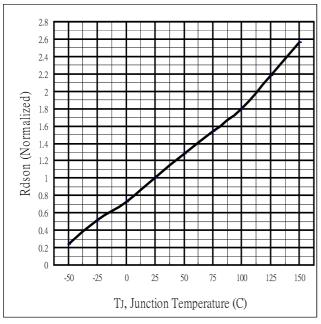


Fig 1. On-Resistance Vs. Temperature

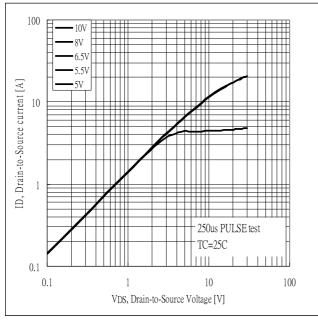


Fig 3. Typical Output Characteristics

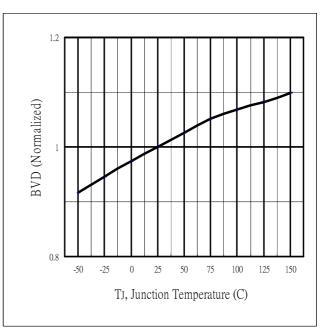


Fig.2 Breakdown Voltage Variation vs. Temperature

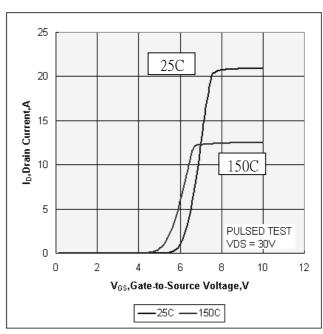


Fig 4. Typical Transfer Characteristics





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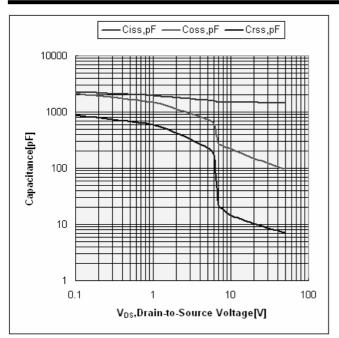


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

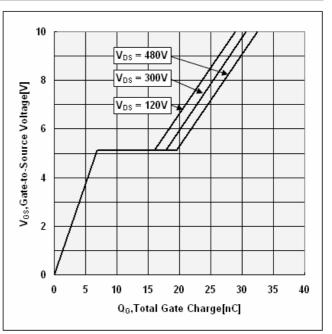


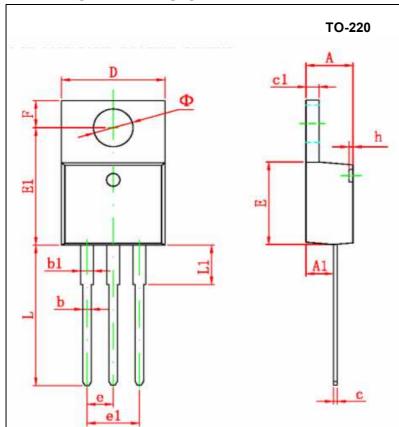
Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage





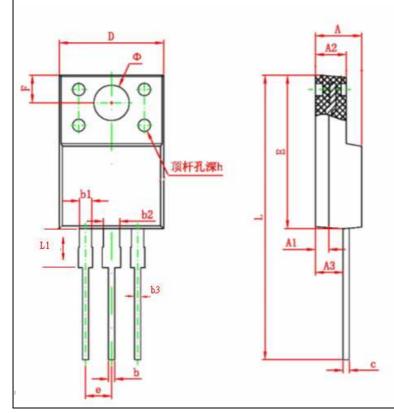
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### **PACKAGE DIMENSION**



a 1 1	Dimensions In Millimeter		
Symbol	Min.	Max	
Α	4.40	4.80	
A1	2.10	2.84	
Ъ	0.71	0.91	
b1	1.17	1.37	
С	0.30	0.60	
c1	1.17	1.47	
D	9.40	10.60	
Е	8.40	9.60	
е	2.54 TYP.		
e1	4.90	5.60	
F	3.00 REF.		
Φ	3.50 REF.		
ħ	0.00	0.30	
L	12.50	14.00	
L1	3.50	4.00	

#### TO-220F



C11	Dimensions In Millimeters		
Symbol	Min.	Max	
Α	3.80	4.70	
A1	1.3 REF.		
A2	2.20	3.20	
A3	2.10	3.20	
Ъ	0.30	0.95	
b1	1.00	1.75	
b2	1.00	1.75	
b3	0.50	0.80	
С	0.30	0.90	
D	9.90	10.40	
Е	14.60	16.20	
е	2.54 TYP.		
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	28.00	30.00	
Ll	3.20	3.55	





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### **IMPORTANT NOTICE**

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